

Asia will help the CPMT membership throughout the world as many CPMT members need to interact with partners, contractors and sub-contractors in Asia. Most Asian countries lack a learned technical society such as CPMT. It should be an opportunity for CPMT to expand its membership base.



KWANG-LUNG LIN (M'98, SM'05) received his Ph.D. in Metallurgy from the Department of Materials Science and Engineering of Pennsylvania State University in 1984. He has been with the Department of Materials Science and Engineering (MSE) of National Cheng Kung University (NCKU) since 1985. He has assumed the Director General of the Department of International Cooperation of the National Science Council (NSC) of Taiwan since January 2005. Before joining the faculty position at NCKU, he did a one year postdoc research at Ames Lab-Iowa State University. He was the Director of the Institute of Micro-Nano Technology of NCKU (August~December 2004), the Coordinator of the Metal and Ceramic Program of NSC (2001~2004), the Director of the Precious Instrument Center of NCKU (1998~2001), and the Department Head of the MSE-NCKU (1991~1994). He has served in several international academic society committees including the Materials and Processing Committee-ECTC of IEEE-CPMT, Board Committee Member-IEEE CPMT (Taipei Chapter), Electronic Packaging and Interconnection Materials Committee of TMS, Surface Engineering Committee of TMS. He has aggressively served in co-organizing international academic symposia, as program committee, or as session chairman in the areas of surface modification, electronic packaging and Pb-free solder. The recent activities he has been involved since 2000 include EMAP (2000~2003), Pb-free Solder Symposium of TMS (2003~2005), and ECTC (2004~2006).

The areas of particular interest to Professor Lin are flip chip technology, solder bumping, and Pb-free solders. Part of most important research achievements is the successful development of a new Sn-Zn series solder as well as the understanding of the solid/liquid solder interaction mechanism and interfacial behavior. Professor Lin has published more than 135 international journal refereed papers and given more than 50 presentations in international academic conferences. He has been awarded 16 patents from USA, Japan, and Taiwan in flip chip, solder bumping, and Pb-free solders. He has also received Best Paper Award -Silver Medal (Plating and Surface Finishing Society (USA, 1997), Distinguished Research Award (NSC, 1997, 1999), Outstanding Engineering Professor Award (Chinese Engineering Society-Taiwan, 1997), C. T. Ho Distinguished Award (2006). He has been invited to deliver invited papers and keynote speeches in many international conferences, the most recent speech was at the International Conference on Nanotechnology and Advanced Materials (Hong Kong, 2006) on a subject of Pb-free solder. He has been serving as referee for a variety of international academic journals as well as project reviewers of the funding agencies of various countries. He is currently the editor of Materials Chemistry and Physics (Elsevier publisher).

He has also been serving as consultant to major electronic packaging industries in Taiwan. A great number of Ph.D.

and MS graduates of his group are serving in major electronic packaging industry in Taiwan. Professor Lin is listed (biography) in Who's Who in the World (Marquis Who's Who, 1996), Who's Who in Science and Engineering, (Marquis Who's Who, 1997), Who's Who in Asia and the Pacific Nations (IBC, Cambridge, 1999), Asia Men & Women of Achievement (Reguerdon & Co., Malaysia, 2003), Asia's Who of Men & Women of Achievement (Rifacimento International Publisher, New Delhi, India, 2003), Who's Who in Asia (Marquis Who's Who, 1st ed., to be published in 2007).

IEEE CPMT SOCIETY REPORT

IEEE FELLOWS ELEVATED AS OF JANUARY 2007

The following is the list of the CPMT Society Members that were elevated to IEEE Fellow Status as of January, 2007. The first 6 in the below list were evaluated by the CPMT Society's Fellows Committee, and the others by another Society's.

Jose Schutt-Aine
University of Illinois
155 Everitt Laboratory
1406 W. Green Street
Urbana, IL, 61801, USA

for contributions to modeling and simulation of distributed circuits with applications to signal integrity

Tawfik Rahal-Arabi
Intel Corporation
13300 SW Ascension Dr.
Tigard, OR, 97223, USA

for contributions in the area of microprocessor high speed bus and power delivery designs

Jusheng Ma
Tsinghua University, China
Department of Materials Science and Engineering
Beijing, 100084, China

for contributions to electronic materials and packaging technology

Hiroshi Yamada
Toshiba Corporation
1, Komukai Toshiba-cho, Saiwai-ku
Kohoku-ku, Yokohama, 212-8582, Japan

for contributions to packaging technology of integrated circuits

Philip Ho Chan
Hong Kong University of Science and Technology
School of Engineering
Clear Water Bay
Kowloon, Hong Kong

for contributions to the development of low-cost flip-chip technology

Ho-Ming Tong
Advanced Semiconductor Engineering (ASE) Group
26 Chin 3rd Road, Nantze Export Processing Zone
Kaohsiung, 811, Taiwan

for leadership in leading-edge integrated circuits technology

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Also the following CPMT-associated new Fellows who were evaluated by other Societies:

Charvaka Duvvury
Texas Instruments, Inc.
Dallas, TX, USA

for contributions to electrostatic discharge devices and design protection methods for integrated circuit applications

Flavio Canavero
Electronics Department
Politecnico di Torino
Torino, Italy

for contributions to the modeling of circuit and electronic interconnects

Leslie Thomas Falkingham
Vacuum Interrupters Limited
Rugby, Warwickshire, United Kingdom

for contribution to the development and commercialization of vacuum interrupter technology

Antonio Orlandi
University of L'Aquila
L'Aquila, Italy

for contributions to high-speed digital systems

Member Recognition:

Dr. Johan Liu Received Prestigious 2006 Magnolia Silver Award

Dr. Johan Liu received the 2006 Magnolia Silver Award from the Shanghai Municipal People's Government, China for his outstanding contribution to the development of Shanghai City.

Dr Liu is a professor at Chalmers University of Technology, Sweden and a special recruited professor at Shanghai University, China and a fellow of IEEE. He serves as a member-at-large of the Board-of Governors and as a region 8 strategic director for IEEE CPMT Society. In 2003 he set up the Sino-Swedish Microsystem Integration Technology (SMIT) Center with the support of Gothenburg City Government of Sweden and Shanghai City Government of China. Today he serves as the director for the SMIT Center as well as the director for the Key State Laboratory of New Displays and System Applications (Chinese Ministry of Education), Shanghai University, China. The Center is actively involved in building up exchange between Sweden and China and conducting application-driven research within the field of microsystems packaging and manufacturing for a number of global players including Intel, Hitachi, Sumitomo and Flextronics.

He was honoured with this award together with a number of top management level personalities from multi-national



companies active in China including: Meiwei Cheng, CEO, China, Ford Co Ltd., USA; Christian Augsten, CEO, Siemens International Trade Co Ltd., Germany; Ding Yi Jin, CEO China Co Ltd, Philips, The Netherlands; William Molim Siu, VP, Intel, USA. For the whole list of the recipients, please the website

at: www.shfao.gov.cn/wsb/node87/node94/node97/

Conference Reviews:

International Conference in Ukraine "Microwave & Telecommunication Technology" (CriMiCo-2006)

Yuri Poplavk

Central Ukraine ED/MTT/SSCS/CPMT/ComSoc Chapter Chair

Pavel Yermolov

CriMiCo-2006 Chair

At September 11-15 in Sevastopol National Technical University (Crimea, Black Sea) took place big annual international conference CriMiCo-2006. The Conference was supported by IEEE, and represented a wide spectrum of interests in various directions of modern electronics, including components, packaging and technology.

Approximate 350 scientists, engineers and students discussed different topics of modern electronics, Photo 1 and 2. More than 300 reports were presented at 4 plenary and 36 technical sessions by scientists and specialists from 161 universities and companies of Byelorussia, China, Germany, Great Britain, Ireland, Israel, Moldova, Netherlands, Poland, Russia, Spain, Ukraine and USA, Photos 3 and 4. Among them there were such sessions as: "Nanostructures physics and simulation" (10 reports); "Nanoelectronics and nanotechnology application" (6 reports); "Devices based on advanced physical properties" (24 reports); "Technology of materials" (11 reports); "Solid state devices CAD/CAM" (11 reports); "Monolithic integrated circuits" (12 reports); "Passive elements design techniques" (22 reports), and many others sessions devoted to microwave and telecommunication active and passive components as well as to their technology.

Two workshops "Training of radio engineers and specialists in the field of telecommunications" and "Common problems of high school pedagogics" as well as round-table discussion "Biophysical mechanisms of low-intensive mm-waves influence on human organism" will be held simultaneously with the conference. Two large volumes of technical digest (1025 pages in sum) were edited just before conference started that was great advantage for effective discussions. Conference Proceeding (books and CDs) were sent to the leading foreign libraries.

Among the approximately 100 reports, related to the direction "Components, packaging and manufacturing technology", it makes sense to note following reports: "New elementary base of Belorussian Institute INTEGRAL for modern digital automatic telephone stations" (V. Emelyanov), "Q-band low noise receiver module protected against incident signals" (P. Gamuletskaya), "Frequency-selective TV- channel amplifiers based on SAW-filters" (E. Semenov); "Ultra-low small signal insertion loss coplanar MMIC broadband power limiter" (I. Abolduev); "Superconductor single-proton detector for near- and middle IR waves"